

**AMENDMENTS TO THE SPECIFICATION**

Please amend the specification as follows:

Please amend the paragraph ¶ 0036 of the specification as filed, on page 16, lines 2-14, as follows:

[0036] The solder composition 10 used in this embodiment is a mixture of a great number of solder particles 11 and the liquid substance 12 made of fatty ester, which is used for forming the solder bumps on the pad electrodes 22. In one aspect, the solder composition has a mixing ratio of the solder particles less than or equal to 30 wt%. The liquid substance 12 contains a flux component whose reaction temperature is close to the melting point of the solder particle 11, which has such a viscosity that it flows at a normal temperature and deposit in layers on a substrate 20. The solder particles 11 are granular agents that precipitate in the liquid substance 12 towards the substrate 20, having the mixing ratio and the particle diameter to be uniformly dispersible within the liquid substance 12.